

Combine Type Connector (for SIM Card 8pins, microSD™ Card)

SCHG Series



Double-deck for SIM Card (8pins) combine type.



Features

- Two-slot, double-deck structure enables two types cards, the SIM Card (8pins) and microSD™ Card, to be separately inserted.

Applications

- For mobile phones, various personal digital assistants, notebook PCs.

Typical Specifications

Items		Specifications	
Structure	Applicable media	SIM Card 8pins	
		microSD™ Card	
	Mounting type	Surface mounting type	
	Mounting style	Standard mount	
	Media ejection structure	Manual insertion/removal/Push-push type	
Performance	Operating temperature range	-25°C to +70°C	
	Voltage proof	500V AC 1minute	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
Insertion and removal cycle	5,000cycles (SIM Card 8pins) 10,000cycles (microSD™ Card)		

Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.
Push-push type	Standard mount	0	Taping	SCHG1B0100

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

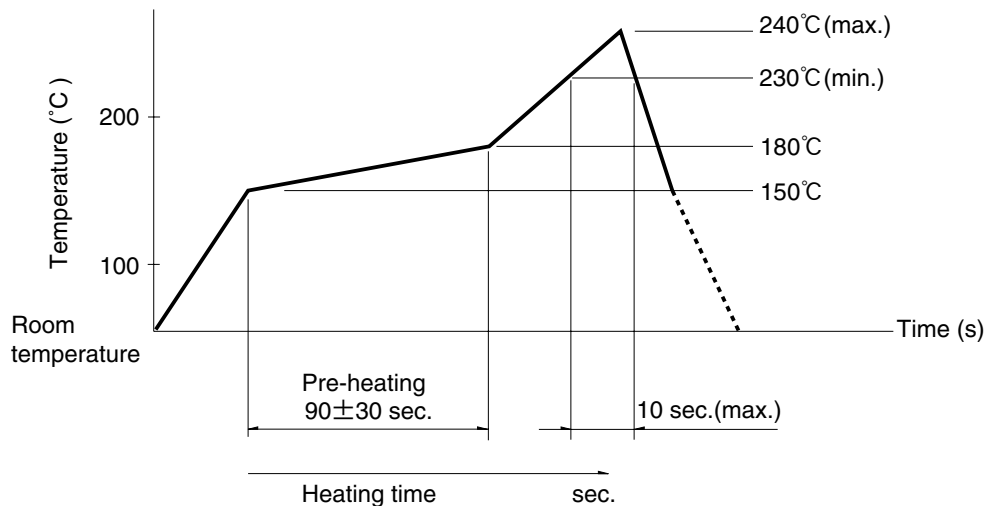
For Express Card™

For CMOS Camera Module

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module

Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.